

Plaskon SMT-B-2FP

Epoxy; Epoxide

Cookson Electronics - Semiconductor Products

Message:

This material is an epoxy molding compound for high temperature, lead-free reflow in fine pitch applications. It is designed to withstand more demanding requirements in moisture performance, occasioned by the higher IR reflow temperatures required for processing lead-free packages. It is a highly filled, multifunctional resin designed to pass JEDEC Level 3 at 240°C IR reflow temperatures.

General Information			
Features	Semi-conductive		
	Low (to no) lead content		
	Low hygroscopicity		
	Fast curing		
	Good formability		
	Heat resistance, high		
Forms	Liquid		
Processing Method	Resin transfer molding		
Physical	Nominal Value	Unit	Test Method
Specific Gravity	1.88	g/cm ³	ASTM D792
Mechanical	Nominal Value	Unit	Test Method
Flexural Modulus			ASTM D790
22°C	1.37	MPa	ASTM D790
240°C	0.147	MPa	ASTM D790
Flexural Strength			ASTM D790
22°C	0.00981	MPa	ASTM D790
240°C	0.00196	MPa	ASTM D790
Thermal	Nominal Value	Unit	Test Method
Glass Transition Temperature	195	°C	ASTM E1356
CLTE - Flow	1.8E-5	cm/cm/°C	ASTM D696
Thermal Conductivity	0.70	W/m/K	ASTM C177
Electrical	Nominal Value	Unit	Test Method
Volume Resistivity	1.0E+15	ohms · cm	ASTM D257
Dielectric Strength	16	kV/mm	ASTM D149
Dielectric Constant (1 kHz)	4.00		ASTM D150
Flammability	Nominal Value	Unit	Test Method
Flame Rating (3.18 mm)	V-0		UL 94
Additional Information			

Recommended Storage Temperature: <5°C Life @ 5°C, defined as not more than 40% loss of spiral flow based on original values.: 24 months Life @ 22°C, defined as not more than 40% loss of spiral flow based on original values.: 8 days Life @ 35°C, defined as not more than 40% loss of spiral flow based on original values.: 3 days Spiral Flow, 175°C, 1000 psi: 160 cm Shimadzu Viscosity, 175°C, 1000 psi: 25 poise Ram Follower Gel Time, 175°C, 1000 psi: 15 sec Ash Content: 78.5 % Hydrolyzable Halides: <1 ppm Moisture Absorption, 85°C/85%RH, 168 hrs: 0.55% Cull Hot Hardness, Shore D: 75 Volume Resistivity, 22°C: 1e15 ohm-cm Volume Resistivity, 150°C: 1e12 ohm-cm All test specimens are transfer molded and post cured for 4 hours at 175°C
Linear Thermal Expansion, Alpha 1: 18 cm⁻⁶/cm/°C
Linear Thermal Expansion, Alpha 2: 60 cm⁻⁶/cm/°C

Injection instructions

Resin Transfer Molding:

Molding Temperature: 170 to 185°C

Molding Pressure: 750 to 1250 psi

In Mold Cure Time: 70 to 120 sec

Post Mold Cure Time, 175°C: 0 to 3 hr

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